

Declaration, Power of Attorney, and Petition

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name,

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled Method for manufacturing a combined solid immersion lens
(SIL) and submicron aperture, and device thereof

the specification of which
(check one) ☒ is attached hereto. ☐ was filed on _____ as

Application Serial No. _____ and was amended on _____ (if applicable).

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, § 1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code § 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)

| | | | |
|-----------|-----------------|------------------------|---|
| 092100404 | Taiwan, R.O.C., | January 9, 2003 | Priority claimed |
| (Number) | (Country) | (Day/month/year filed) | <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No |
| _____ | _____ | _____ | <input type="checkbox"/> Yes <input type="checkbox"/> No |
| (Number) | (Country) | (Day/month/year filed) | <input type="checkbox"/> Yes <input type="checkbox"/> No |
| _____ | _____ | _____ | <input type="checkbox"/> Yes <input type="checkbox"/> No |

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, § 1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

| | | | |
|--------------------------|---------------|----------|--------------------------------|
| (Application Serial No.) | (Filing date) | (Status) | (patented, pending, abandoned) |
| _____ | _____ | _____ | _____ |

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

And I hereby appoint

BUCKNAM AND ARCHER
Joseph J. Orlando Reg. # 25,218
Fernanda M. Fiordalisi # 20,938
Allison C. Collard # 22,532
1077 Northern Blvd.
Roslyn, New York 11576

my attorney with full power of substitution and revocation, to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith.

Wherefore I pray that Letters Patent be granted to me for the invention or discovery described and claimed in the foregoing specification and claims, and I hereby subscribe my name to the foregoing specification and claims, declaration, power of attorney, and this petition.

Full name of sole or first inventor..... Wensyang Hsu.....
Inventor's signature..... Wensyang Hsu..... Date..... May 28 2003
Room 406, Engineering Hall 5, Dept. of Mechanical Engineering,
Residence..... 1001, Ta Hseuh Rd., Hsin Chu 300, Taiwan, R.O.C......
Citizenship..... Taiwan.....
Post Office Address..... same as above.....

Full name of second joint inventor, if any..... Hsueh Liang Chou.....
Second Inventor's signature..... Hsueh Liang Chou..... Date..... June 2, 2003
Room 406, Engineering Hall 5, Dept. of Mechanical Engineering,
Residence..... 1001 Ta Hseuh Rd., Hsin Chu 300, Taiwan, R.O.C......
Citizenship..... Taiwan.....
Post Office Address..... Same as Above.....

Full name of third joint inventor, if any..... Chung Hao Tien.....
Third Inventor's signature..... Chung-Hao Tien..... Date..... June 03, 2003
Residence..... 12th Floor, No.14-1, Sanmin Rd., Hsintien City, Taipei County
Citizenship..... Taiwan..... Taiwan, R.O.C.
Post Office Address..... Same as above.....

Full name of fourth joint inventor, if any.....
Fourth Inventor's signature..... Date.....
Residence.....
Citizenship.....
Post Office Address.....

Full name of fifth joint inventor, if any.....
Fifth Inventor's signature..... Date.....
Residence.....
Citizenship.....
Post Office Address.....

(Supply similar information and signature for third and subsequent joint inventors)